


Application No. 10/024,269  
Preliminary Amendment dated January 22, 2004

**Remarks**

Applicants have canceled claims 1-44, and added new claims 45-57. Claims 45-57 remain in the application. Applicants are also enclosing a copy of a translation of a Japanese Laid Open Patent No. 52-118390 originally submitted in an Information Disclosure Statement filed on July 30, 2003.

Applicants respectfully submit that the application is now in condition for allowance and reconsideration of the application is respectfully requested. The Examiner is invited to contact the undersigned in order to resolve any outstanding issues and expedite the allowance of this application.

Respectfully submitted,

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**(54) IC WAFER TRANSPORTING CONTAINER**

**(21) Application No.: Showa 51/33213**

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